

Smartphone Dismantling Manual For Recycling and Material Recovery

Device: HMD Arc and Aura²

Model identifier : TA-1697, TA-1682

1. Introduction

Purpose of the document and compliance with the Ecodesign Directive,
This document provides dismantling instructions for the HMD Fusion smartphone in accordance with the Ecodesign Directive and WEEE requirements. It supports sustainable design and end-of-life treatment for recycling and material recovery. The dismantling procedure is aligned with Directive 2012/19/EU (WEEE) and IEC TR 62635-2012 guidelines. Always return your used electronic products, batteries, and packaging materials to dedicated collection points. This way you help prevent uncontrolled waste disposal and promote the recycling of materials. Electrical and electronic products contain a lot of valuable materials, including metals (such as copper, aluminum, steel, and magnesium) and precious metals (such as gold, silver, and palladium). Materials in the device can be recovered as materials and energy. The recovery and recycling rates achieved are 78.4% and 75.4%, respectively, compliant with required thresholds. The device can be sent for recycling with HMD. Guidance can be found under following link:
www.hmd.com/en_int/device-recycling

2. Safety Precautions

1. Electrical safety: Power off the device and allow battery to discharge below 25% before disassembly. Disconnect all external accessories.
2. Handling of sharp parts and hazardous materials: Use gloves and ESD protection when handling internal components. Be cautious with the lithium-ion battery to avoid puncture or fire risk.

3. Preparation Steps

1. Remove your personal data from the device. Detailed instructions can be found in the User guide
2. Power off the device completely or let it drain to below 25%.
3. Remove SIM and memory cards using a SIM ejector tool.
4. Disconnect all accessories and cables.

Please refer to the following documents for additional instructions, if needed:

- User guide: www.hmd.com/en_int/support
- Repair guide: www.hmd.com/en_int/self-repair

4. Disassembly Process

Detailed step-by-step disassembly guides are available on our self-repair pages: www.hmd.com/en_int/self-repair. The images below only illustrate the basic steps. Please make sure to review the full instructions before attempting any complex procedures.

Opening the Housing

- Remove the SIM tray.



Insert the opening pick under the back cover and Slide the opening pick along the side



Battery Removal

Add the PH00 bit into screwdriver and remove the screw from the top deco.



Remove the battery : Fold the edges of battery tape, so have a smooth grip on them, Start to lift the battery on both sides using the tape

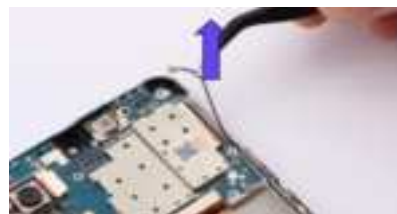


Mainboard and Module Extraction

Unscrew the screw on the top section of the main board, Disconnect main board flex connector ,disconnect the sub back camera connector.



- Remove front camera, Disconnect RF cable and separate main board



5. Material Sorting and Identification

Plastics:

- Screen protector films, internal insulation layers, plastic housing components.

Metals:

- Screws, shielding, claspboards, connectors, coils, magnets.

Glass:

- LCD and cover glass from screen module.

Hazardous Components:

- Li-ion battery (Model E): Requires special handling and recycling.

6. Environmental and Legal Notes

1. WEEE compliance:

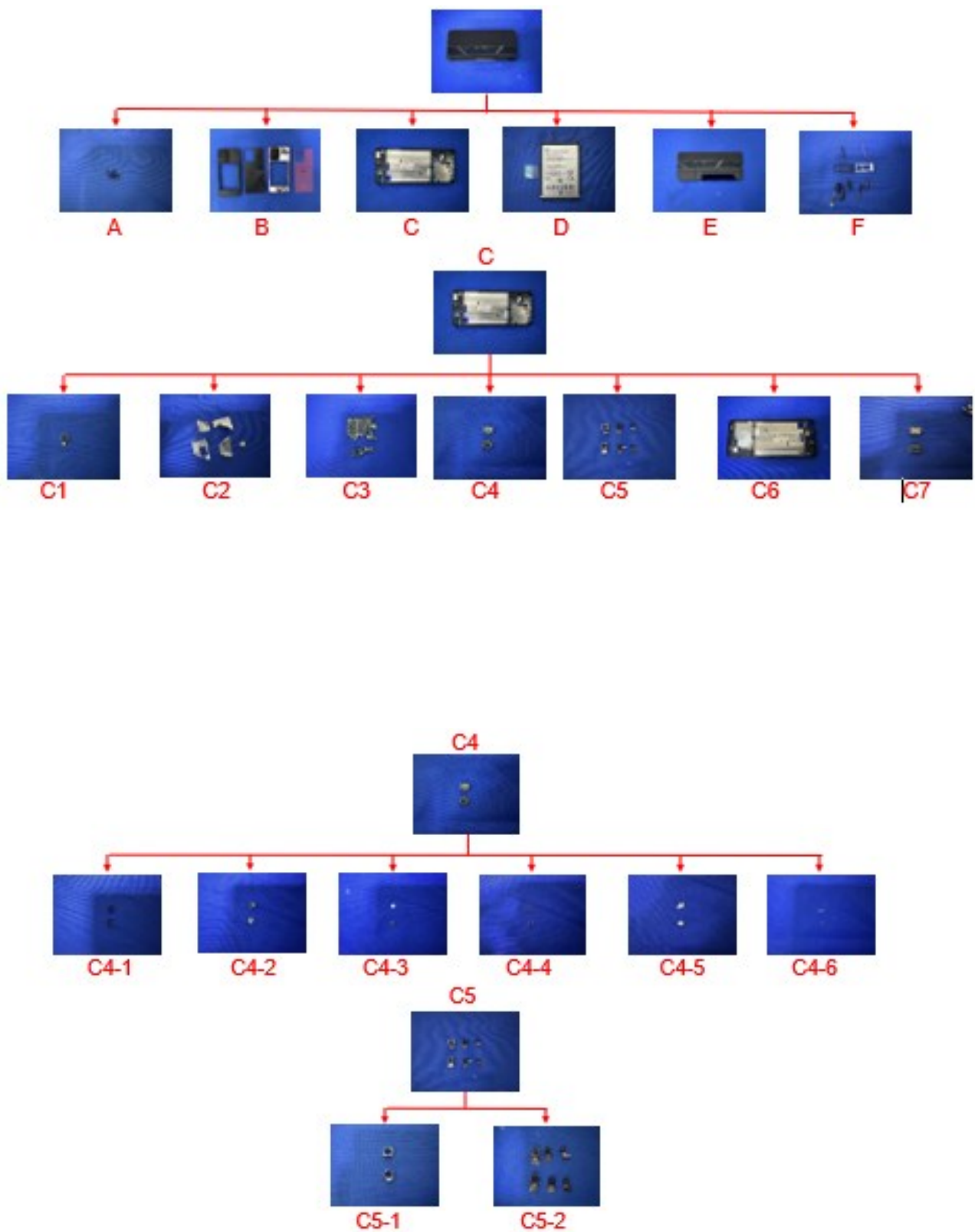
1. Classified as "Small IT and telecommunication equipment" under WEEE.
2. Compliant with Annex VII requirements (selective treatment, hazardous materials separation).

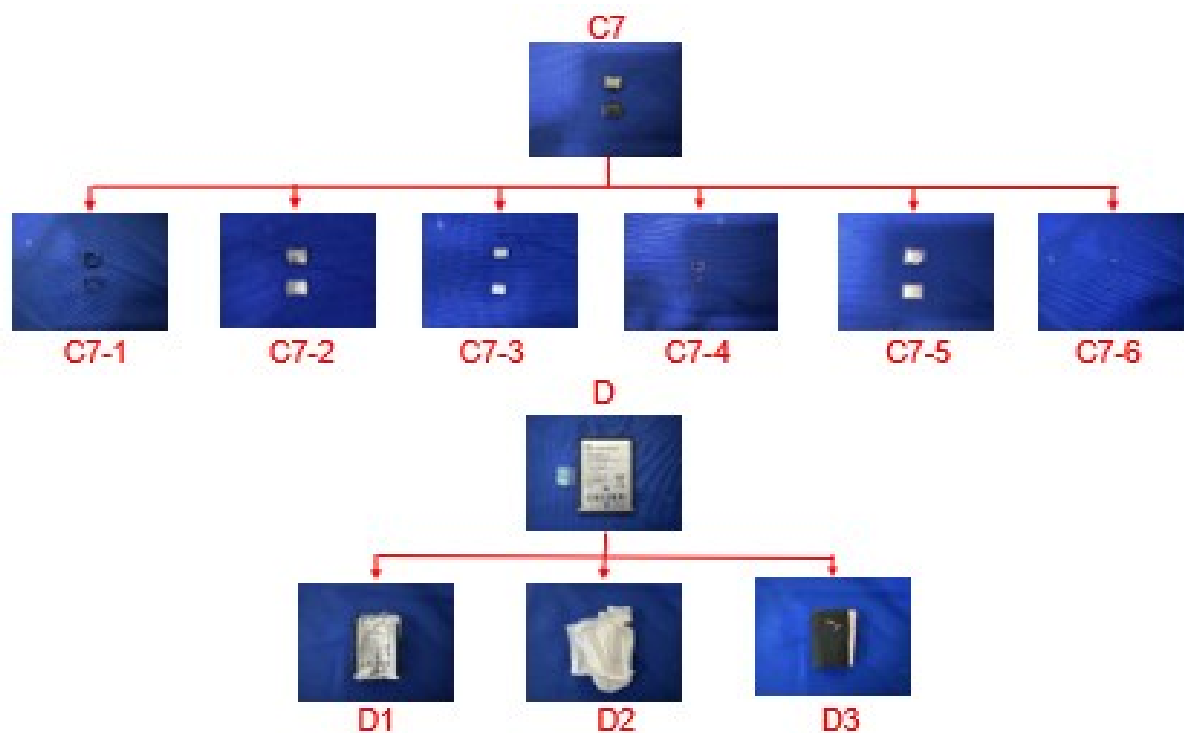
2. Notes on recyclable vs non-recyclable components

1. Most parts are recyclable (metal components ~94%, plastic ~90%).
2. Some complex modules (mainboard, battery) require selective treatment.

7. Annexes

1. Detailed disassembly guidance with material description TA -1697



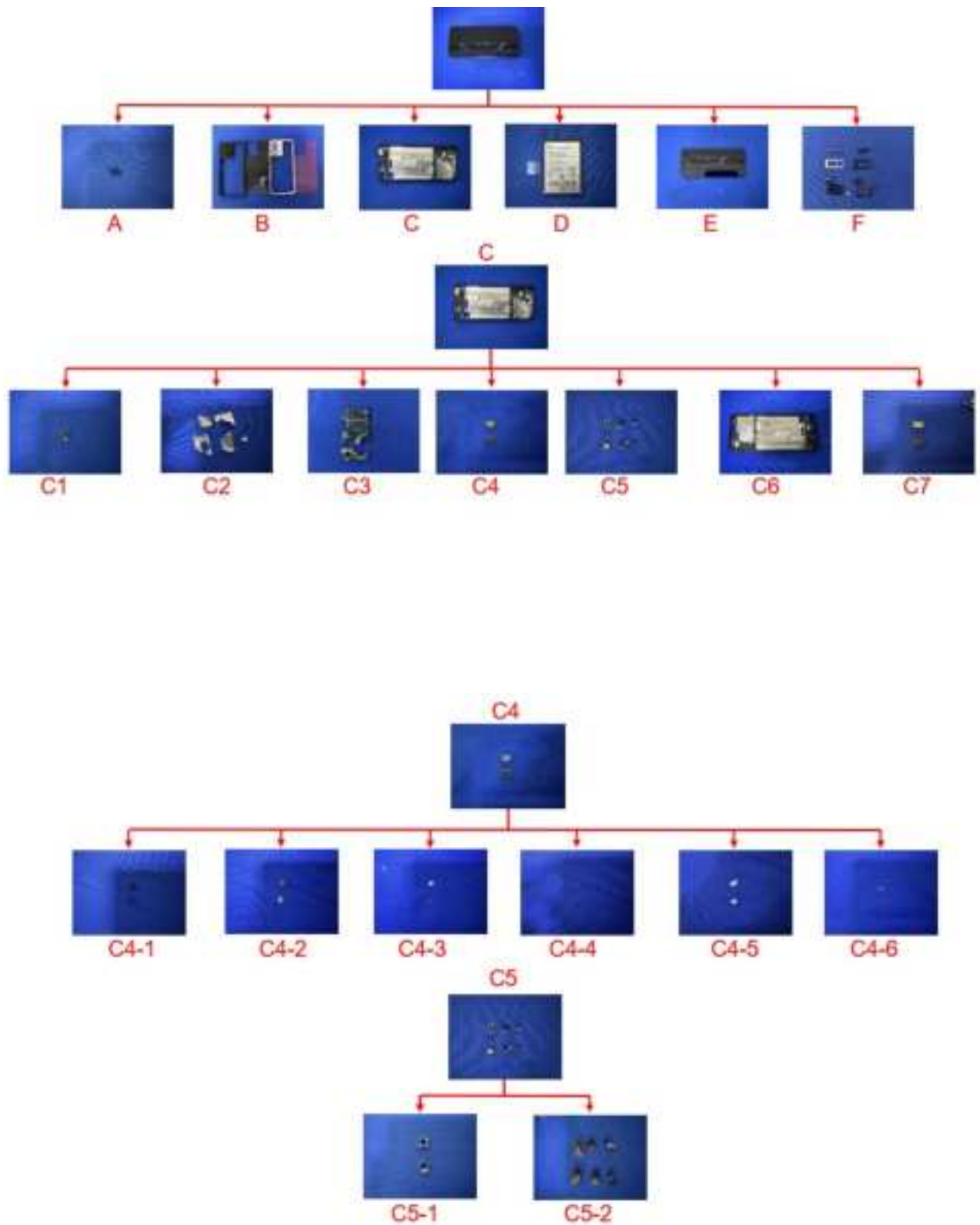


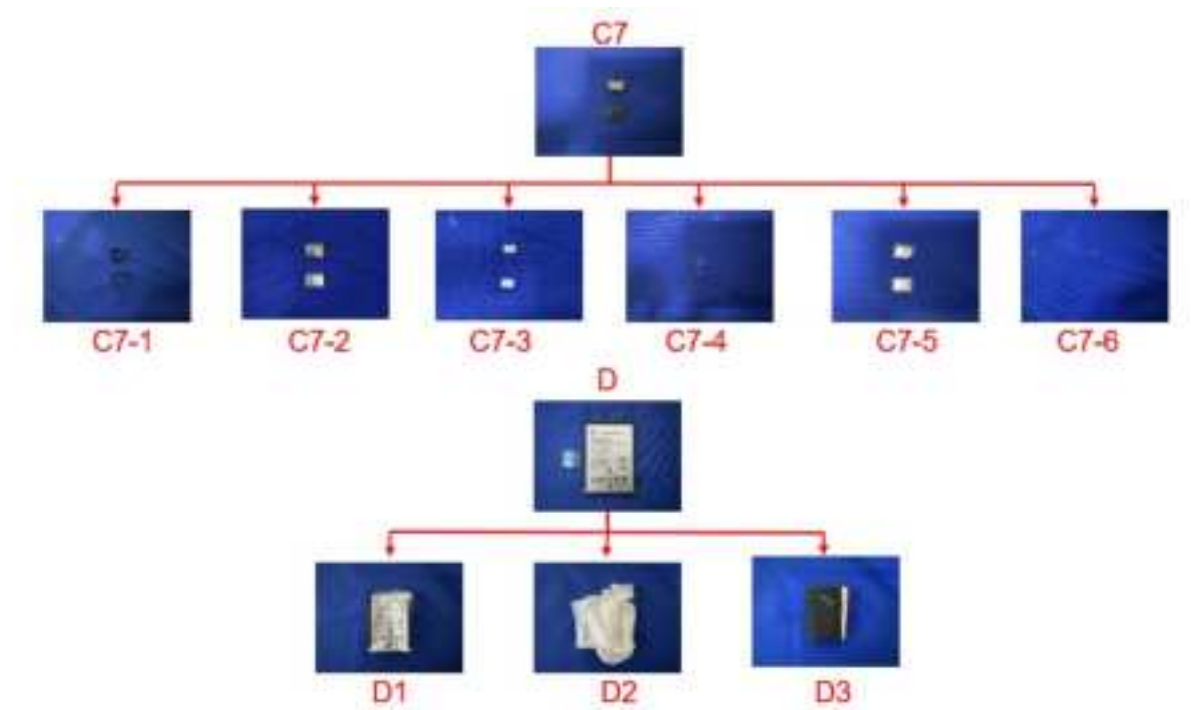
2. List of main components and materials TA -1697

No.	Name of Parts	Material	Quantity
A	Screw	Metal	16
B	Shell	Complex	2
C	Mainboard	PCB Complex	1
C1	Motor	Complex	1
C2	Metal shield cover	Metal	5
C3	Mainboard	PCB	2
C4	Receiver	Complex	1
C4-1	Plastic shell	Plastic	1
C4-2	Metal shell	Metal	1
C4-3	Magnet	Metal	1

C4-4	Copper coil	Metal	1
C4-5	Silver paper	Plastic	1
C4-6	Metal pins	Metal	2
C5	Camera	Complex	3
C5-1	Metal shell	Metal	1
C5-2	Camera	Plastic	3
C6	Clapboard	Metal	1
C7	Speaker	Complex	1
C7-1	Plastic shell	Plastic	1
C7-2	Metal shell	Metal	1
C7-3	Magnet	Metal	1
C7-4	Copper coil	Metal	1
C7-5	Silver paper	Plastic	1
C7-6	Metal pins	Metal	2
D	Battery	Complex	1
D1	Plastic shell	Plastic	1
D2	Plastic film	Plastic	1
D3	Battery	Complex	1
E	LCD	Complex	1
F	Keypad	Plastic	3

3. Detailed disassembly guidance with material description TA -1682



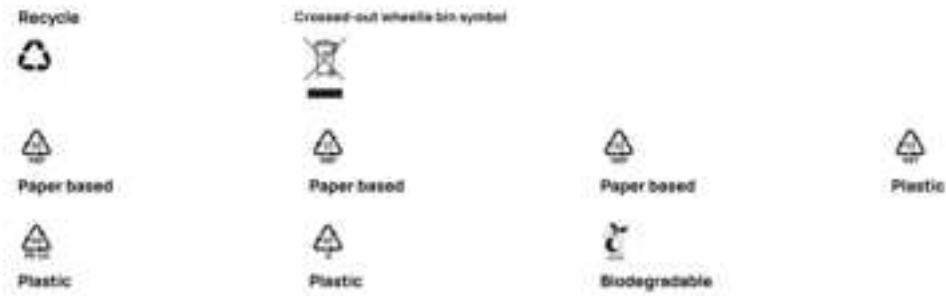


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5. Recycling logos used in Nokia/HMD products



Sources:

WEEE ASSESSMENT REPORT: No. 24T04Z100999-023 prepared by: CTTL, Telecommunication Technology Labs, China Academy of Information and Communication Technology.

For further and more detailed information, please contact us at: sustainability@hmdglobal.com.